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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

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Alan G. Wood
William M. Hiatt
James M. Wark
David R. Hembree
Kyle K. Kirby
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Serial No.: 10/730,333

ART UNIT:

Filing Date: 12/08/2003

EXAMINER:

For: WAFER LEVEL METHODS FOR FABRICATING
MULTI-DICE CHIP SCALE SEMICONDUCTOR
COMPONENTS (AS AMENDED)

Attorney Docket No. 02-1500.1

PRELIMINARY AMENDMENT

January 31, 2005

Mail Stop Amendment
Commissioner of Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This Preliminary Amendment is being submitted prior to the first Office Action on the merits. Please amend the application as follows.